

ECOFREC™ 200



Low residue no-clean air or nitrogen atmosphere

FEATURES

ECOFREC™ 200 is a no clean flux recommended for soldering either with air or nitrogen controlled atmosphere. Good solder joints without solderballing are achieved with this low residue flux.

ECOFREC™ 200 is compatible with a wide range of solder mask.

SPECIFICATIONS

Density at 20°C	0,798 - 0.806
Flash point	16°C
Dry extract, 3 H at 105°C	2 %
Halogen content	no halide
Acid index, KOH/G mg	18

CHARACTERISTICS

Its halogen-free activation system is eliminated after wave soldering, leaving no visible residue on the PCB.

Electrical performances are especially high after ageing in a humidity chamber, with a SIR value on inter digit IPC B 24 comb close to 10^5 Megohms under storage conditions of 21 days at 40°C, 93 % RH, 5 Volts, or 7 days at 85°C, 85 % RH, 50 Volts (IPC TM 650 2.6.3.3 Rev A).

AUTOMATIC CONTROL - PIN POINT TESTER

Due to the absence of any residue after soldering, **ECOFREC™ 200** ensures that no electrical contact failure or “false failure” will take place during the automatic control on pin point tester.

PACKAGING

Plastic drum

20 litres

STORAGE & SHELF LIFE

ECOFREC™ 200 must be stored in a cool and well-ventilated area (between 5° and 30°C), in securely closed packaging. Its maximum shelf life is a year.

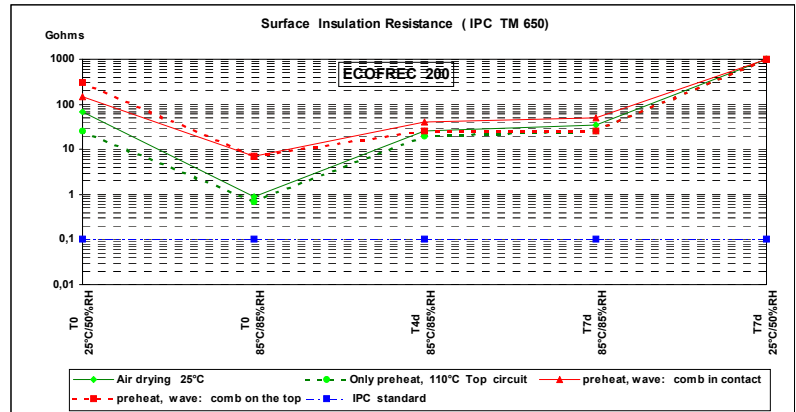
ECOFREC™ 200 must be stored at room temperature for 12 hours before use.

PROCESS PARAMETERS

ECOFREC™ 200 can exclusively be applied by spraying, atomisation under air or nitrogen pressure, or with ultrasounds.

Preheating temperature must be set so as to achieve from 120°C to 140° under the PCB prior to entering the solder wave, that is 110°C to 130°C on topside of PCB.

Residue removal, and thus good cosmetic aspect of PCB will be obtained through the temperature level achieved after preheat and solderwave.



Using nitrogen allows for a higher flexibility of use when the application requires to increase preheat temperature in order to reduce thermal shock, and thus to provide for a better removal of flux residues.

And more especially, the nitrogen atmosphere provides for a significantly better soldering of components, regardless of their oxidation level.

HSE

ECOFREC™ 200 must be handled in a well-ventilated room, away from any flames. Fumes must be evacuated from flux and solder work stations by means of an efficient exhaust.

Please refer to Material Safety Data Sheet before use.

No issues when used as recommended.

Although the conformity to ROHS 2002/95CE applies to EQUIPMENT put on the market and not to a component in particular, we warranty that this product contains less than 0.1% of mercury, lead, chromium VI, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and less than 0.01% for the cadmium, in accordance with the decision of The European Commission dated 18/08/2005, fixing the maximal concentration values.

This data is based on information that the manufacturer believe to be reliable and offered in good faith. In no event will INVENTEC be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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